Special Issue

Design, Fabrication and Reliability of Semiconductor Devices

Message from the Guest Editor

Dear colleagues, Emerging materials and devices are steadily becoming core features of future applications. Fabrication and process techniques are key parameters that affect the function of related devices due to unavoidable defects generated during the material process and device fabrication. Research on material processing and device/IC fabrication is very important in order to improve the quality of devices, as well as that of integrated circuits and systems. New materials have been proven to provide potential high functionality, reliability, and prolong the lifetime of the device/systems in application. Combing both studies in emerging materials and advanced fabrication techniques can make a big difference for future applications. This Special Issue can make both emerging material research and advanced fabrication process more accessible to researchers in various fields and accelerate innovation in the field of semiconductor devices and ICs. Accordingly, this Special Issue seeks to showcase research papers and review articles that focus on novel methodological developments in emerging materials, such as 2D materials, 3D IC and system integration fabrication processes.

Guest Editor

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